

N-Ch 20V Fast Switching MOSFETs

Product Summary



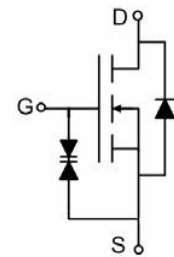
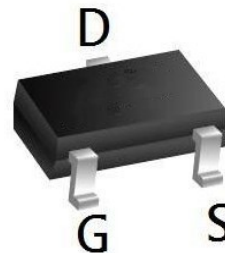
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

BVDSS	RDS(on)	ID
20V	145mΩ	0.75A

Description

The XR3134 is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(on) and efficiency for most of the small power switching and load switch applications. The XR3134 meet the RoHS and Green Product requirement with full function reliability approved.

SOT523 Pin Configuration



Absolute Maximum Ratings (TA=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units	
V _{DSS}	Drain-Source Voltage	20	V	
V _{GSS}	Gate-Source Voltage	±10	V	
I _D	Continuous Drain Current	T _A = 25°C	0.75	A
		T _A = 100°C	0.5	A
I _{DM}	Pulsed Drain Current ^{note1}	3	A	
P _D	Power Dissipation	T _A = 25°C	0.17	W
R _{θJA}	Thermal Resistance, Junction to Case	735	°C/W	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C	

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V,	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±10V	-	-	±10	uA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.0	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note2</small>	V _{GS} =4.5V, I _D =0.5A	-	145	190	mΩ
		V _{GS} =2.5V, I _D =0.4A	-	225	315	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1.0MHz	-	60	-	pF
C _{oss}	Output Capacitance		-	22	-	pF
C _{rss}	Reverse Transfer Capacitance		-	12	-	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =0.75A, V _{GS} =4.5V	-	1	-	nC
Q _{gs}	Gate-Source Charge		-	0.28	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	0.22	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =10V, I _D =0.5A, R _{GEN} =10Ω, V _{GS} =4.5V	-	2	-	ns
t _r	Turn-on Rise Time		-	19	-	ns
t _{d(off)}	Turn-off Delay Time		-	10	-	ns
t _f	Turn-off Fall Time		-	23	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	0.75	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	3	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =0.75A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure 1: Output Characteristics

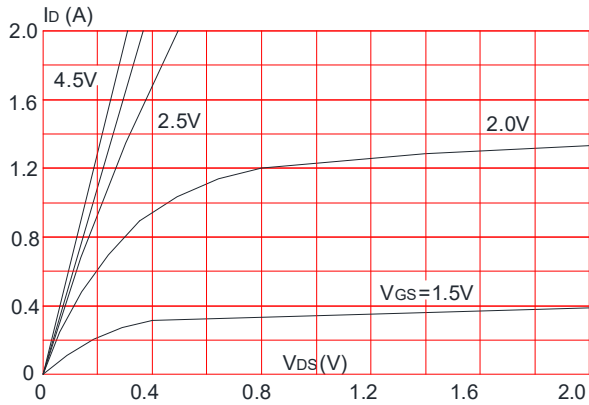


Figure 2: Typical Transfer Characteristics

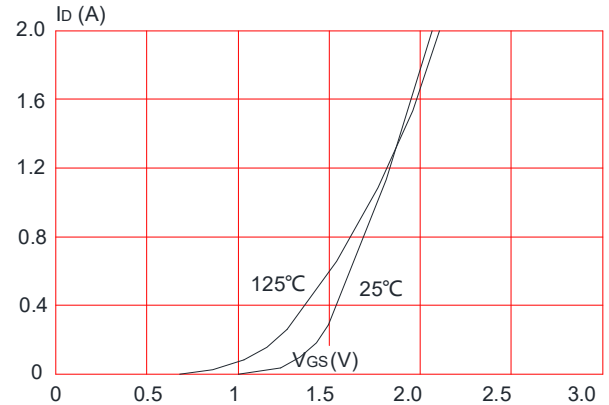


Figure 3: On-resistance vs. Drain Current

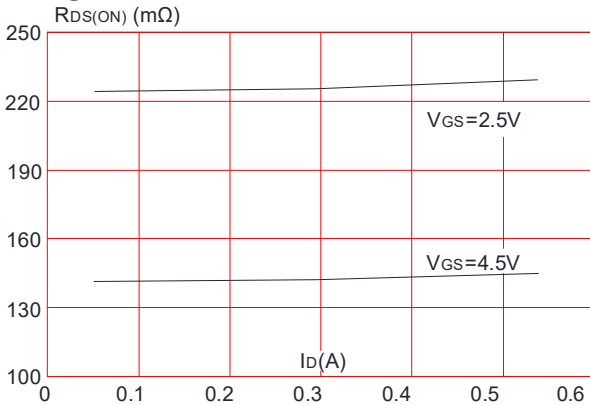


Figure 4: Body Diode Characteristics

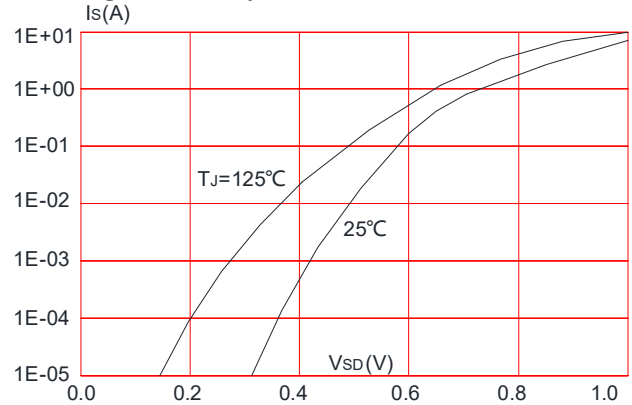


Figure 5: Gate Charge Characteristics

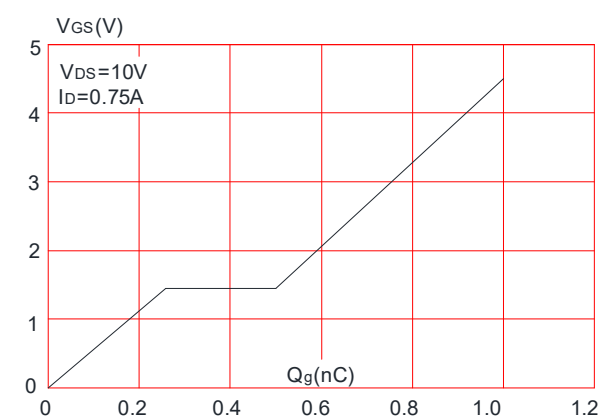
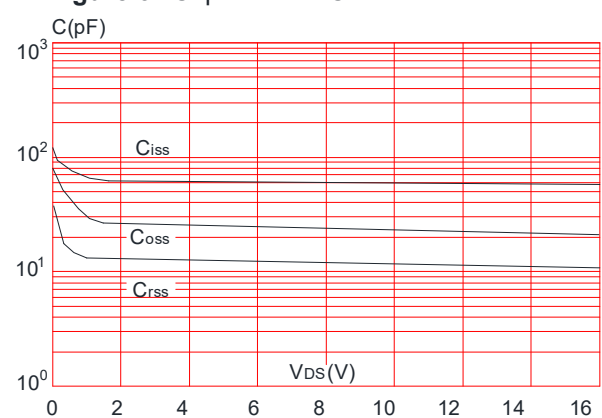


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

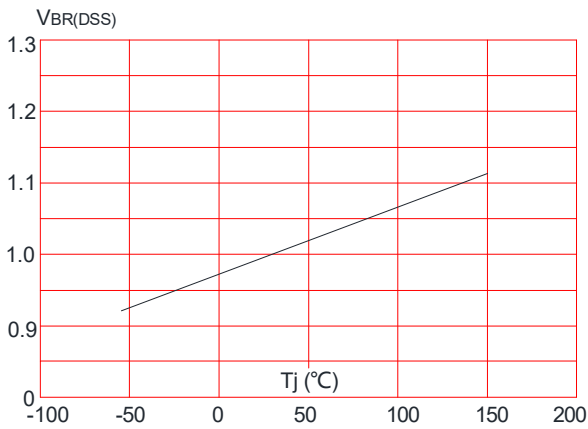


Figure 8: Normalized on Resistance vs. Junction Temperature

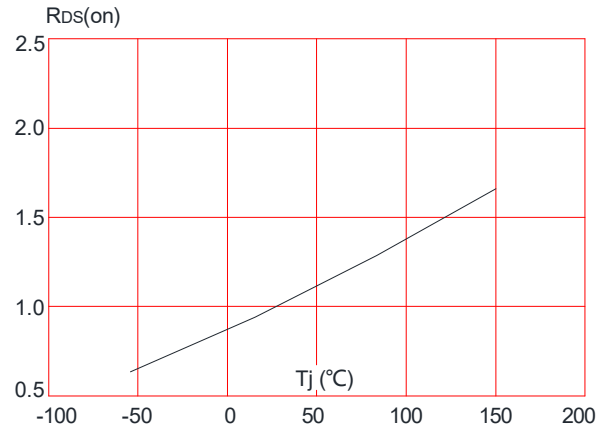


Figure 9: Maximum Safe Operating Area

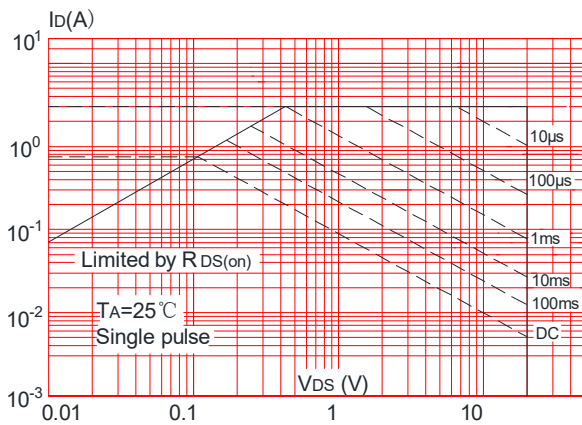


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

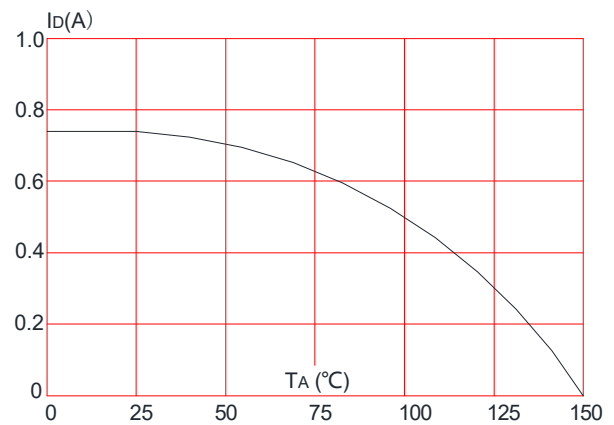
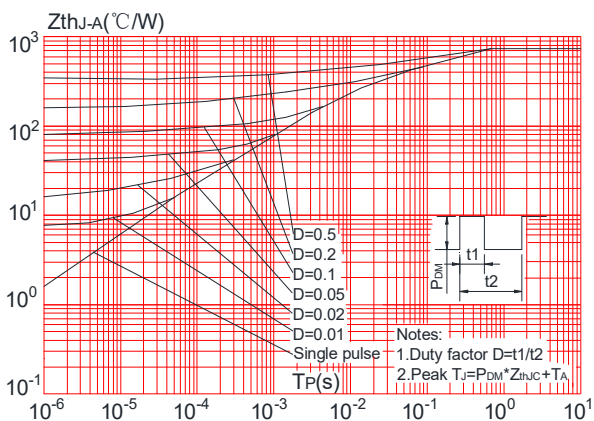
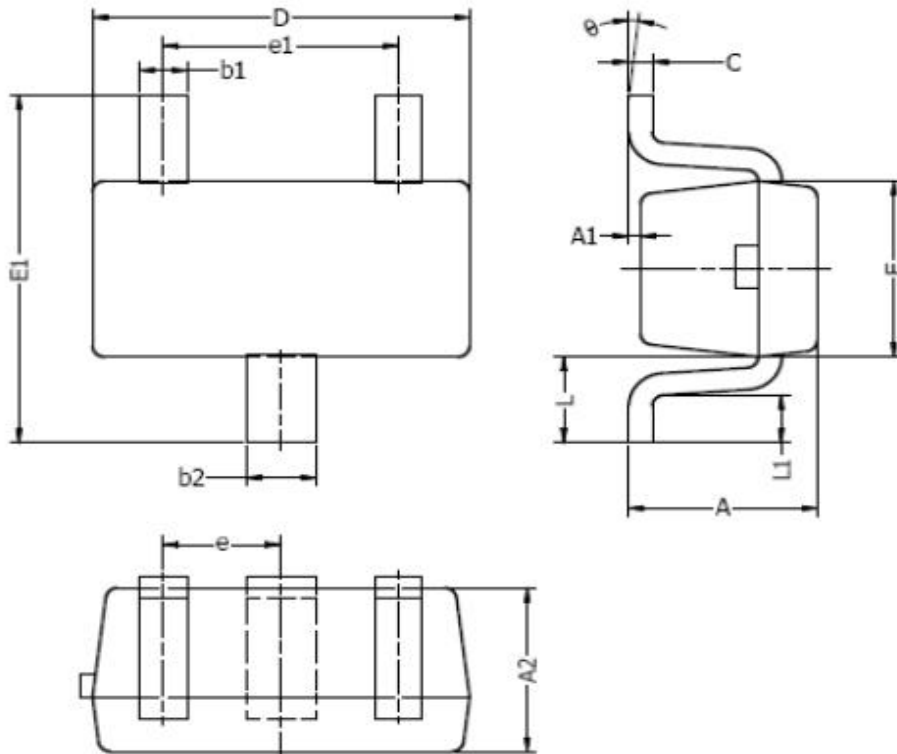


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Package Mechanical Data-SOT-523-3L



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
A2	0.70	0.80	0.028	0.031
b1	0.15	0.25	0.006	0.010
b2	0.25	0.35	0.010	0.014
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
E1	1.45	1.75	0.057	0.069
e	0.50 TYP.		0.020 TYP.	
e1	0.90	1.10	0.035	0.043
L	0.40 REF.		0.016 REF.	
L1	0.10	0.30	0.004	0.012
θ	0°	8°	0°	8°

NOTES:

1. Above package outline conforms to JEITA EAJ ED-7500A SC-75A.
2. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.